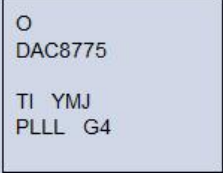
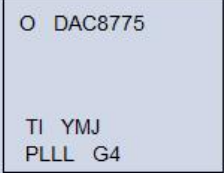




PCN Number:	20180314000	PCN Date:	Mar 15, 2018
Title:	Device Topside Marking Change for DAC8775IRWFR/T Device		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:	<input type="checkbox"/> Assembly Site <input type="checkbox"/> Assembly Process <input type="checkbox"/> Assembly Materials <input type="checkbox"/> Mechanical Specification <input checked="" type="checkbox"/> Packing/Shipping/Labeling <input type="checkbox"/> Design <input type="checkbox"/> Data Sheet <input type="checkbox"/> Part number change <input type="checkbox"/> Test Site <input type="checkbox"/> Test Process <input type="checkbox"/> Wafer Bump Site <input type="checkbox"/> Wafer Bump Material <input type="checkbox"/> Wafer Bump Process <input type="checkbox"/> Wafer Fab Site <input type="checkbox"/> Wafer Fab Materials <input type="checkbox"/> Wafer Fab Process		
PCN Details			
Description of Change:			
Texas Instruments Incorporated is announcing an information only notification for a device topside marking change for DAC8775IRWFR/T Device			
Reason for Change:			
Continuity of Supply			
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):			
None			
Changes to product identification resulting from this PCN:			
CURRENT		PROPOSED	
Top side Symbol:  O – Pin 1 (Marked)		Top side Symbol:  O – Pin 1 (Marked)	
			
Product Affected:			
DAC8775IRWFR		DAC8775IRWFT	

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com